

### **Features**

- Compact, space-saving 1206 footprint
- Low profile and symmetrical design
- Small size enables fast response time to thermal runaway events
- Ultra-low resistance
- RoHS compliant\*
- Agency recognition: 🕰 🛳

### **Additional Information**

Click these links for more information:









PRODUCT TECHNICAL INVENTORY SAMPLES
SELECTOR LIBRARY

# CONTACT

# P-TCO-N Series - Polymeric Thermal Cutoff Device

# **Electrical Characteristics**

	Vmax	lmax	I <sub>hold</sub>	Thermal Cutoff		Max. Time To Trip		Resistance		Certifications	
Model	VIII III III III III III III III III II		at 23 °C	at 3 A	at 2 A	at 23 °C		Ohms at 23 °C		cUL	ΤÜV
	Volts	Amps	Amps	°C	°C	Amps	Seconds	R <sub>Min</sub> .	R <sub>1Max</sub> .	E174545	R50405491
P-TCO-N350/12	12	50	3.5	75 ±20	90 ±15	8.0	5.0	0.002	0.022	✓	✓
P-TCO-N400/12	12	50	4.0	80 ±15	95 ±15	10.0	5.0	0.002	0.018	✓	✓
P-TCO-N450/12	12	50	4.5	85 ±15	100 ±10	22.5	2.0	0.002	0.014	1	/

### **Environmental Characteristics**

Operating Temperature	40 °C to +85 °C	
Storage Condition		
Before Opening	. +40 °C max. / 70 % RH max.	
After Opening	+40 °C max. / 10 % RH max.	
Floor Condition After Opening	. Consumption within 4 weeks at floor condition +30 °C	max. / 60 % RH max.
Passive Aging	. +85 °C, 1000 hours ±10	% typical resistance change
Humidity Aging	+85 °C, 85 % R.H. 100 hours ±15	% typical resistance change
Thermal Shock	. +85 °C to -40 °C, 20 times ±30	% typical resistance change
Solvent Resistance	. MIL-STD-202, Method 215 No	change (marking still legible)
Vibration	. MIL-STD-883C, Method 2007.1, No	change (R <sub>min</sub> <r<r<sub>1max)</r<r<sub>
	Condition A	- That
Moisture Sensitivity Level (MSL)	. See Note	
ESD Classification - HBM	6	

# **Test Procedures and Requirements**

٦	Test State of the	Test Conditions	Accept/Reject Criteria
١	/isual/Mech	Verify dimensions and materials	Per MF physical description
F	Resistance	In still air @ 23 °C	$R_{min} \le R \le R_{1max}$
٦	Fime to Trip	At specified current, Vmax, 23 °C	$T \le max$ . time to trip (seconds)
H	Hold Current	30 min. at I <sub>hold</sub>	No trip
٦	Frip Cycle Life	V <sub>max</sub> , I <sub>max</sub> , 100 cycles	No arcing or burning
٦	Frip Endurance	V <sub>max</sub> , 48 hours	No arcing or burning
5	Solderability	245 °C ±5 °C, 5 seconds	95 % min. coverage

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<sup>\*</sup> RoHS Directive 2015/863, Mar 31, 2015 and Annex.

<sup>\*\*</sup> Bourns considers a product to be "halogen free" if (a) the Bromine (Br) content is 900 ppm or less; (b) the Chlorine (Cl) content is 900 ppm or less; and (c) the total Bromine (Br) and Chlorine (Cl) content is 1500 ppm or less.

Specifications are subject to change without notice. Users should verify actual device performance in their specific applications. The products described herein and this document are subject to specific legal disclaimers as set forth on the last page of this document, and at <a href="https://www.bourns.com/docs/legal/disclaimer.pdf">www.bourns.com/docs/legal/disclaimer.pdf</a>.

# **Applications**

- Thermal protection for USB-C 2.0, 3.0 and 3.1 cables and ports
- Mobile device fast charging port protection

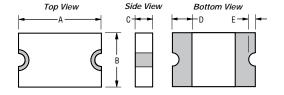
# P-TCO-N Series – Polymeric Thermal Cutoff Device

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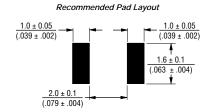
### **Product Dimensions**

Model	A		В		С		D	E	
Wodei	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Min.	Max.
P-TCO-N350/12									
P-TCO-N400/12	3.00 (0.118)	3.50 (0.138)	1.40 (0.055)	1.80 (0.071)	$\frac{0.60}{(0.024)}$	1.10 (0.043)	0.25 (0.010)	0.05 (0.002)	0.45 (0.018)
P-TCO-N450/12		, ,	, ,	, ,	, ,	, ,	, ,		

DIMENSIONS:  $\frac{MM}{(INCHES)}$ 



**Terminal material:** ENIG-plated terminals



## **Packaging Quantity**

3500 pcs. per reel

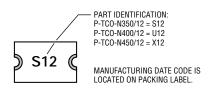
# Thermal Derating Table - Ihold (Amps)

Model	Ambient Operating Temperature									
Wodei	-40 °C	-20 °C	0 °C	23 °C	40 °C	50 °C	60 °C	70 °C	85 °C	
P-TCO-N350/12	5.15	4.66	4.13	3.50	2.98	2.71	2.49	2.00	1.65	
P-TCO-N400/12	5.80	5.25	4.65	4.00	3.40	3.10	2.65	2.20	1.80	
P-TCO-N450/12	6.10	5.40	4.70	4.50	3.60	3.15	2.70	2.25	1.85	

# P-TCO - N 350 / 12 - 2 Polymeric Thermal Cutoff Device N = 1206 footprint Surface Mount Component Hold Current, Ihold 350 - 450 (3.50 Amps - 4.50 Amps) Maximum Voltage, Vmax 12 = 12 Volts Packaging -2 = Tape and Reel Packaged per EIA 481

## **Typical Part Marking**

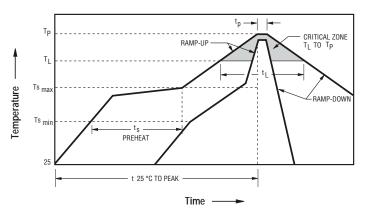
Represents total content. Layout may vary.



# P-TCO-N Series – Polymeric Thermal Cutoff Device

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### **Solder Reflow Recommendations**



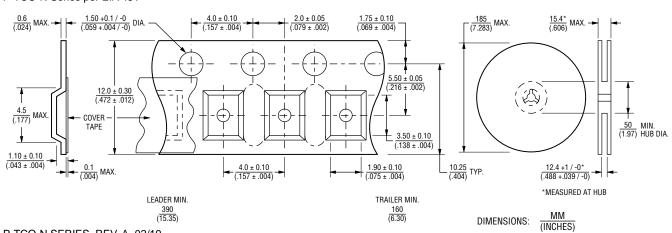
#### Notes:

- P-TCO-N models cannot be wave soldered or hand soldered.
   Please contact Bourns for soldering recommendations.
- All temperatures refer to topside of the package, measured on the package body surface.
- If reflow temperatures exceed the recommended profile, devices may not meet the published specifications.
- Compatible with Pb and Pb-free solder reflow profiles.
- Excess solder may cause a short circuit, especially during hand soldering. Please refer to the Polymeric Thermal Cutoff Soldering Recommendation guidelines.

Profile Feature	Pb-Free Assembly				
Average Ramp-Up Rate (Ts <sub>max</sub> to T <sub>p</sub> )	3 °C / second max.				
PREHEAT:					
Temperature Min. (Ts <sub>min</sub> )	150 °C				
Temperature Max. (Ts <sub>max</sub> )	200 °C				
Time (Ts <sub>min</sub> to Ts <sub>max</sub> ) (ts)	60~180 seconds				
TIME MAINTAINED ABOVE:					
Temperature (T <sub>L</sub> )	217 °C				
Time (t <sub>L</sub> )	60~150 seconds				
Peak Temperature (T <sub>p</sub> )	260 °C				
Time within 5 °C of Actual Peak Temperature (t <sub>p</sub> )	20~40 seconds				
Ramp-Down Rate	6 °C / second max.				
Time 25 °C to Peak Temperature	8 minutes max.				

## **Packaging Specifications**

## P-TCO-N Series per EIA 481



P-TCO-N SERIES, REV. A, 02/19

Specifications are subject to change without notice.

Users should verify actual device performance in their specific applications.

# **Bourns® Polymeric Thermal Cutoff Devices (P-TCO)**

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### **Application Notice**

Users are responsible for independent and adequate evaluation of Bourns® Polymeric Thermal Cutoff (P-TCO) devices in the user's application, including the P-TCO device characteristics stated in the applicable data sheet.

- Polymeric Thermal Cutoff devices must not be allowed to operate beyond their stated maximum ratings. Inadequate adherence
  to such maximum ratings could result in damage to the P-TCO device and lead to electrical arcing and/or fire. Circuits with
  inductance may generate a voltage above the rated voltage of the P-TCO devices and should be thoroughly evaluated within the
  user's application during the P-TCO selection and qualification process.
- Polymeric Thermal Cutoff devices are intended to protect against adverse effects of temporary overtemperature conditions and are not intended to serve as protective devices where such conditions are expected to be repetitive or prolonged.
- As a normal function of operation, Polymeric Thermal Cutoff devices experience thermal expansion under fault conditions.
  Thus, a P-TCO device must be protected against mechanical stress, and must be given adequate clearance within the user's
  application to accommodate such thermal expansion. Rigid potting materials or fixed housings or coverings that do not provide
  adequate clearance should be thoroughly examined and tested by the user, and may result in the malfunction of P-TCO devices
  if the thermal expansion is inhibited.
- Exposure to lubricants, silicon-based oils, solvents, gels, electrolytes, acids, and other related or similar materials may adversely affect the performance of Polymeric Thermal Cutoff devices.
- Aggressive solvents may adversely affect the performance of Polymeric Thermal Cutoff devices. Conformal coating,
  encapsulating, potting, molding, and sealing materials may contain aggressive solvents including but not limited to xylene and
  toluene, which are known to cause adverse effects on the performance of P-TCO devices. Such aggressive solvents must be
  thoroughly cured or baked to ensure complete removal from P-TCO devices to minimize the possible adverse effect on the
  device.
- Recommended storage conditions should be followed at all times. Such conditions can be found on the applicable data sheet
  and on the Polymeric Thermal Cutoff Device Moisture/Reflow Sensitivity Classification (MSL) note: https://www.bourns.com/
  docs/RoHS-MSL/msl\_ptco.pdf

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